# 高速直流電鍍銅製程
# High Speed Direct Current Copper Electroplating Technology

## COPPER GLEAM™ ST-920 Acid Copper

Consistently excellent through hole and microvia conformal plating performance on a vertical DC plating process. Wide effective current density range (10 – 35 A/ft$^2$) with soluble anode.

在直流垂直電鍍製程上，具有穩定且優異的通/盲孔貫孔能力。搭配可溶性陽極，可操作電流密度範圍大 (10 – 35 A/ft$^2$)

### Advantages of COPPER GLEAM™ ST-920 Acid Copper
### COPPER GLEAM™ ST-920 具備以下優越的特性

- Excellent throwing power on through hole and microvia over high current density
  在高電流下仍具備優異的通孔與盲孔貫孔能力
- Superior panel plating distribution
  良好的電鍍均勻度
- Compatibility with both panel and pattern plating process
  可適用於全板或二次銅電鍍製程
- Easily analyzed and controlled by conventional CVS
  控制簡易，並可用CVS分析控制
- Good thermal reliability
  卓越的耐熱信賴度

### Microvia Conformal Plating

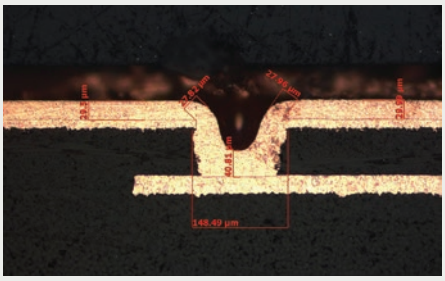

**Figure 1:** Microvia conformal plating
- 150 µm ϕ x 100 µm BMV-Eless
- Throwing Power = 135%

### Through Hole (TP%)

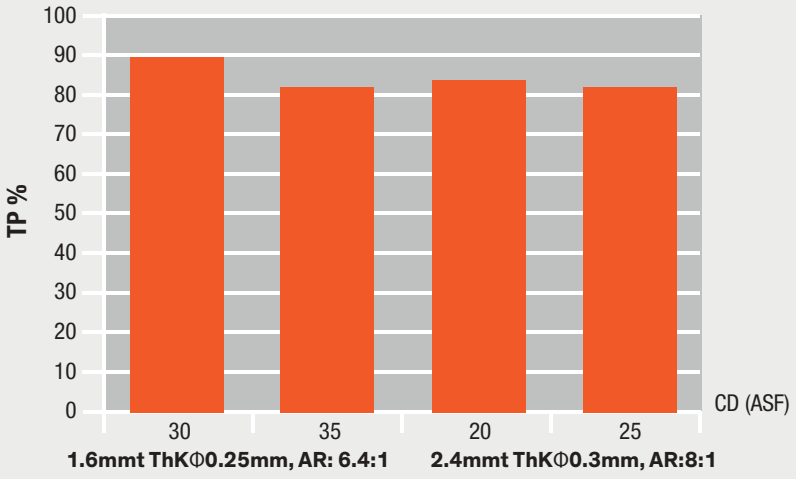


**Figure 2:** Through Hole (TP%) at 1.6 &2.4 mmt board thickness